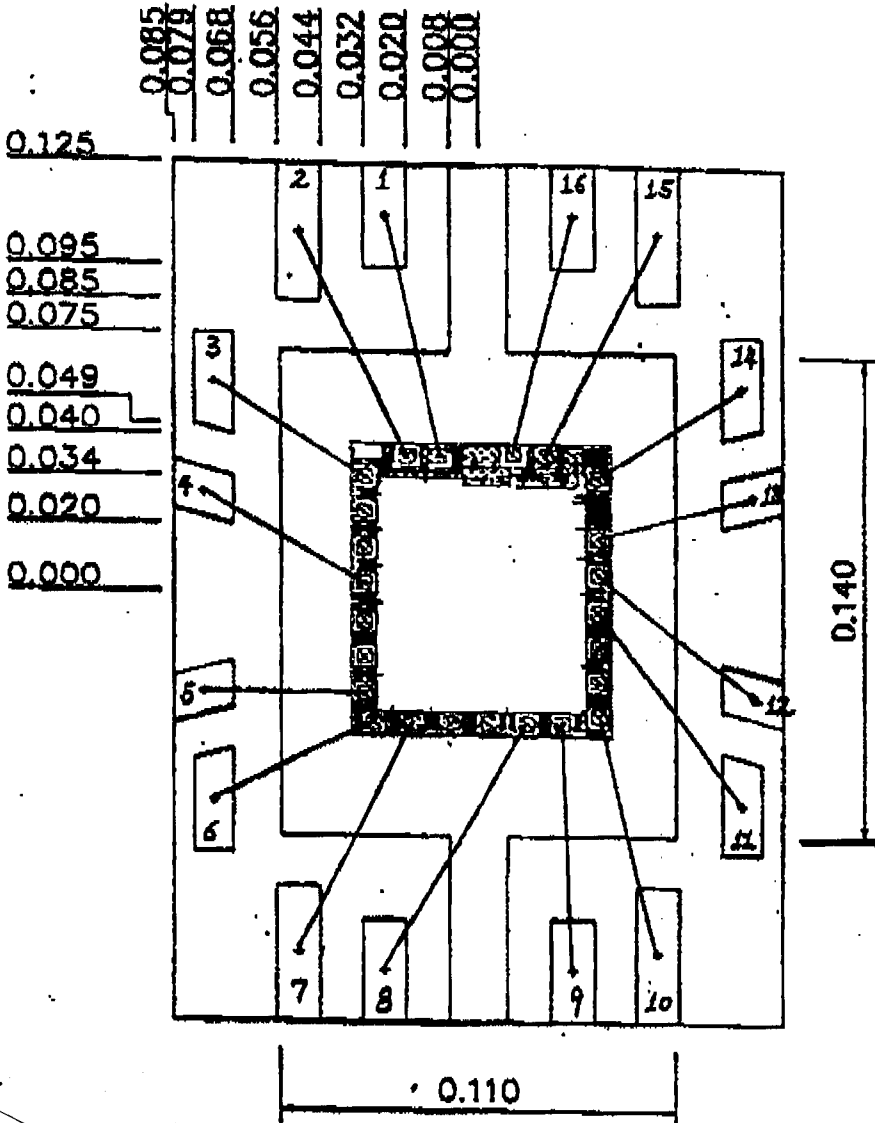


3.1.4 GMS34004

ITEM	DESCRIPTION	CONTENTS
DEVICE	DEVICE NAME	GMS34004
	FUNCTION	REMOTE CONTROL SYSTEM 송신용 MCU
	APPLICATION	<input checked="" type="checkbox"/> COMMERCIAL <input type="checkbox"/> MILITARY
	MAX. CURRENT	1.0 mA
WAFER	CHIP PATTERN NAME	34004
	PASSIVATION	YES
	WAFER THICKNESS	400 μ m
	BACKSIDE METAL	NO
CHIP	CHIP SIZE (BARE CHIP)	X = 1820 μ m, Y = 2170 μ m
	SCRIBE LINE WIDTH	X = 100 μ m, Y = 130 μ m
	MIN. PAD SIZE	100 μ m \times 100 μ m
	NUMBER OF PAD	24EA
PACKAGE	PACKAGE TYPE	16SOP / 16DIP
	LEAD FRAME TYPE	<input checked="" type="checkbox"/> Ag PLATING <input type="checkbox"/> Au PLATING
	PADDLE SIZE	16SOP = 90 \times 110 MIL
		16DIP = 110 \times 140 MIL
	DIE ATTACH	<input type="checkbox"/> EUTECTIC Au PLATING
		<input checked="" type="checkbox"/> EPOXY
		<input type="checkbox"/> POLYIMIDE
WIRE BONDING	GOLD, 1.0 mil, 16BONDS	

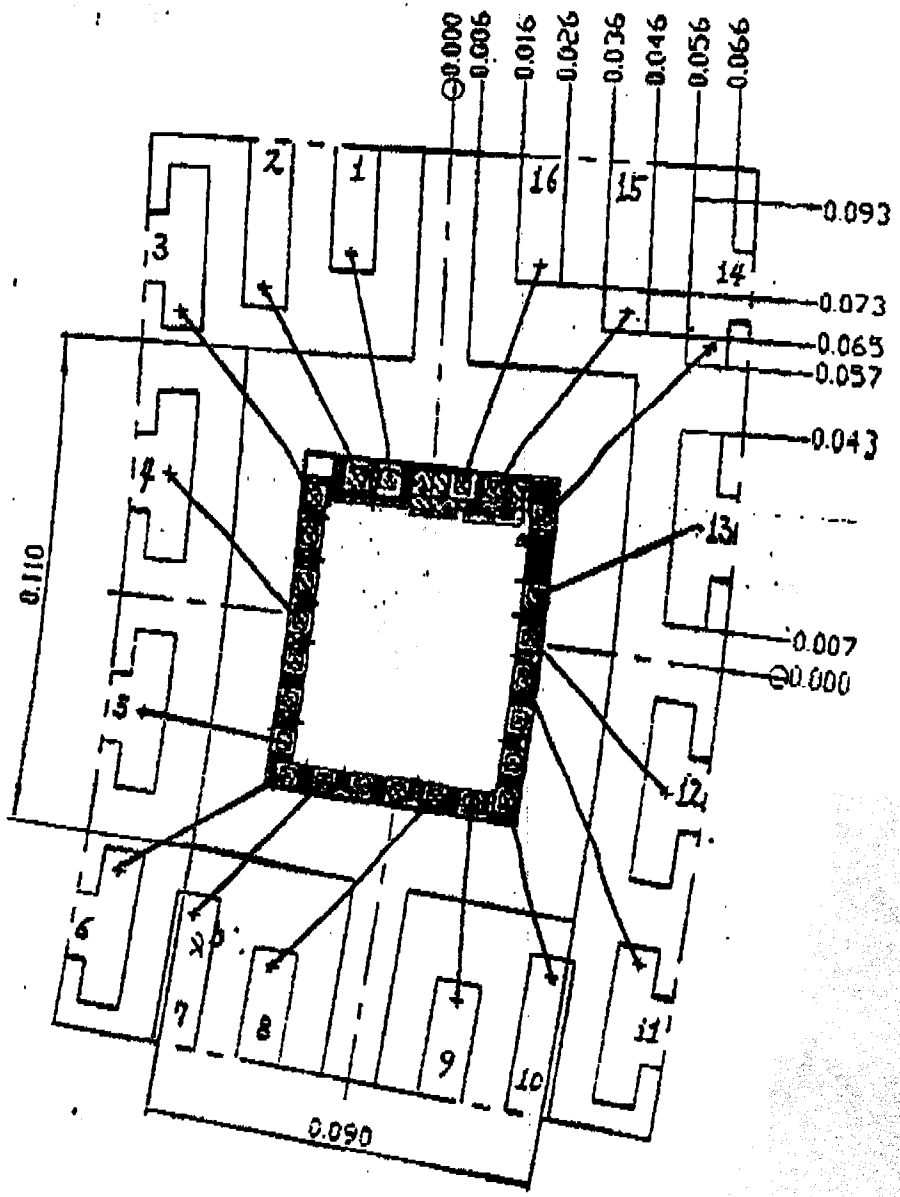
REMARKS

3.3.6 16DIP Bonding Diagram (GMS34004)



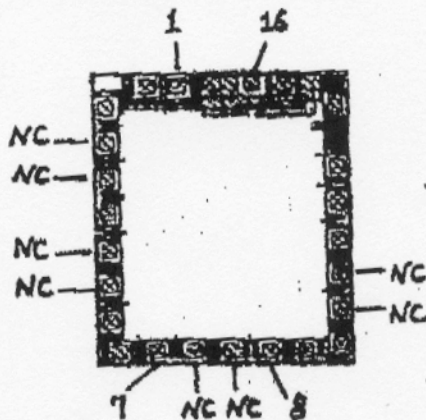
(배율 x 20)

3.3.5 16SOP Bonding Diagram (GMS34004)



(배율 $\times 20$)

PAD LOCATION & NUMBER



BARE CHIP SIZE ==> LOW LEFT : (0, 0)
 UP RIGHT : (1820, 2170)

PAD NO.	PAD 좌표 (X, Y)	PAD NO.	PAD 좌표 (X, Y)
1	(615.6, 2070)	9	(1471.2, 95.0)
2	(386.8, 2085)	10	(1722.8, 153.8)
3	(95.0, 1913.8)	11	(1722.8, 930.8)
4	(95.0, 1124.8)	12	(1722.8, 1197.6)
5	(95.8, 318.2)	13	(1722.8, 1466.0)
6	(157.8, 95.8)	14	(1722.0, 1916.6)
7	(425.2, 95.0)	15	(1358.8, 2070)
8	(1216.0, 95.0)	16	(1130.0, 2085)